

Title (en)  
Grinding or cleaning apparatus

Title (de)  
Schleif-oder Putzeinrichtung

Title (fr)  
Dispositif de meulage ou de polissage

Publication  
**EP 1092503 A3 20030917 (DE)**

Application  
**EP 00810917 A 20001004**

Priority  
DE 19948996 A 19991011

Abstract (en)  
[origin: EP1092503A2] Card wire is ground or cleaned by a grinding device incorporating an elastic layer (22), e.g. expanded foam, with a grinding medium (23), e.g. corundum particles, embedded throughout the material. The wire penetrates partly into the material. The device can be a complete or sectionalized roller and suction is provided to remove abraded material.

IPC 1-7  
**B24B 19/18**; **B24D 13/12**

IPC 8 full level  
**B24B 19/18** (2006.01); **B24D 13/02** (2006.01); **D01G 15/38** (2006.01)

CPC (source: EP US)  
**B24B 19/18** (2013.01 - EP US); **B24D 13/02** (2013.01 - EP US); **D01G 15/38** (2013.01 - EP US)

Citation (search report)  
• [DXY] DE 19739187 A1 19990311 - TRUETZSCHLER GMBH & CO KG [DE]  
• [YA] WO 9916579 A1 19990408 - RIETER AG MASCHF [CH], et al  
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Designated contracting state (EPC)  
AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE

DOCDB simple family (publication)  
**DE 19948996 A1 20010412**; EP 1092503 A2 20010418; EP 1092503 A3 20030917; US 6508698 B1 20030121

DOCDB simple family (application)  
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